

MATERIAL DECLARATION SHEET



Material Number	PTVS15-058C-SH			
Product Line	Semiconductor products			
Compliance Date	September 1 st 2013			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.736600	Bisphenol Epoxy Resin	1675-54-3	40.00	6.01	15.02
				Epoxy Resin	25085-99-8	20.00	3.00	
				Crystalline Silica	14464-46-1	23.00	3.45	
				Brominated Epoxy Resin	40039-93-8	12.00	1.80	
				Iron Oxide	51274-00-1	2.00	0.30	
				Titanium Oxide	13463-67-7	3.00	0.45	
2	Electrodes	Copper	2.644175	Copper	7440-50-8	99.10	53.42	53.91
				Silver	7440-22-4	0.40	0.22	
				Other	-	0.50	0.27	
3	Terminations	Copper	1.079846	Copper	7440-50-8	99.50	21.91	22.02
				Other	-	0.50	0.11	
4	Termination Finish	Silver	0.015288	Silver	7440-22-4	100.00	0.31	0.31
5	Chip	Silicon Die	0.212811	Silicon	7440-21-3	85.34	3.70	4.34
				Aluminium	7429-90-5	5.13	0.22	
				Nickel	7440-02-0	9.09	0.39	
				Gold	7440-57-5	0.44	0.02	
6	Die Attach	Solder	0.160574	Lead	7439-92-1	92.50	3.03	3.27
				Tin	7440-31-5	5.00	0.16	
				Silver	7440-22-4	2.50	0.08	
7	Die Coating	Silicone	0.055570	Polysiloxane	63148-62-9	22.11	0.25	1.13
				Chromium Sesquioxide	1308-38-9	5.67	0.06	
				Fumed Silica	112945-52-5	11.11	0.13	
				Filler	trade secret	61.11	0.69	
Total Weight			4.904864					